

IN THE CLAIMS

1. (Original) A semiconductor package comprising:
a package substrate;
a semiconductor chip attached to the substrate;
a TIM formed on the semiconductor chip;
a dam that substantially surrounds the TIM; and
a lid placed over the TIM to contact a surface thereof,
wherein the dam is formed on the substrate and in contact with the sides of the TIM and the semiconductor chip, wherein the lid further comprises a supporter for supporting the dam, and wherein the lid comprises injection holes through which materials required to form the dam and TIM are injected.
2. (Original) The semiconductor package of claim 1, wherein the lid is attached to the substrate via a sealant and covers the semiconductor chip and the dam.
3. (Original) The semiconductor package of claim 1, wherein the dam is formed of a material that is not liquefied at least below about 125°C.
4. (Original) The semiconductor package of claim 3, wherein the material that is not liquefied below about 125°C comprises a thermosetting epoxy.
5. (New) The semiconductor package of claim 1, wherein the injection holes comprise a first hole and a second hole, the first hole overlying the dam, the second hole overlying substantially the center portion of the TIM.